

Eight-Channel, High Speed, $\pm 60V$, $\pm 1.0A$, Ultrasound RTZ Pulser

Features

- ▶ HVCMOS technology for high performance
- ▶ High density integrated ultrasound transmitter
- ▶ 0 to $\pm 60V$ output voltage
- ▶ $\pm 1.0A$ source and sink current in pulse mode
- ▶ $\pm 1.0A$ source and sink current in RTZ mode
- ▶ Up to 20MHz operating frequency
- ▶ Matched delay times
- ▶ Optional clock re-alignment
- ▶ 3.3V CMOS logic interface and reference
- ▶ +3.3V low voltage supply for V_{DD}
- ▶ Built-in linear regulators for floating gate driver
- ▶ Built-in output drain diodes & bleed resistors

Application

- ▶ Portable medical ultrasound imaging
- ▶ Piezoelectric transducer drivers
- ▶ Pulse waveform generator

General Description

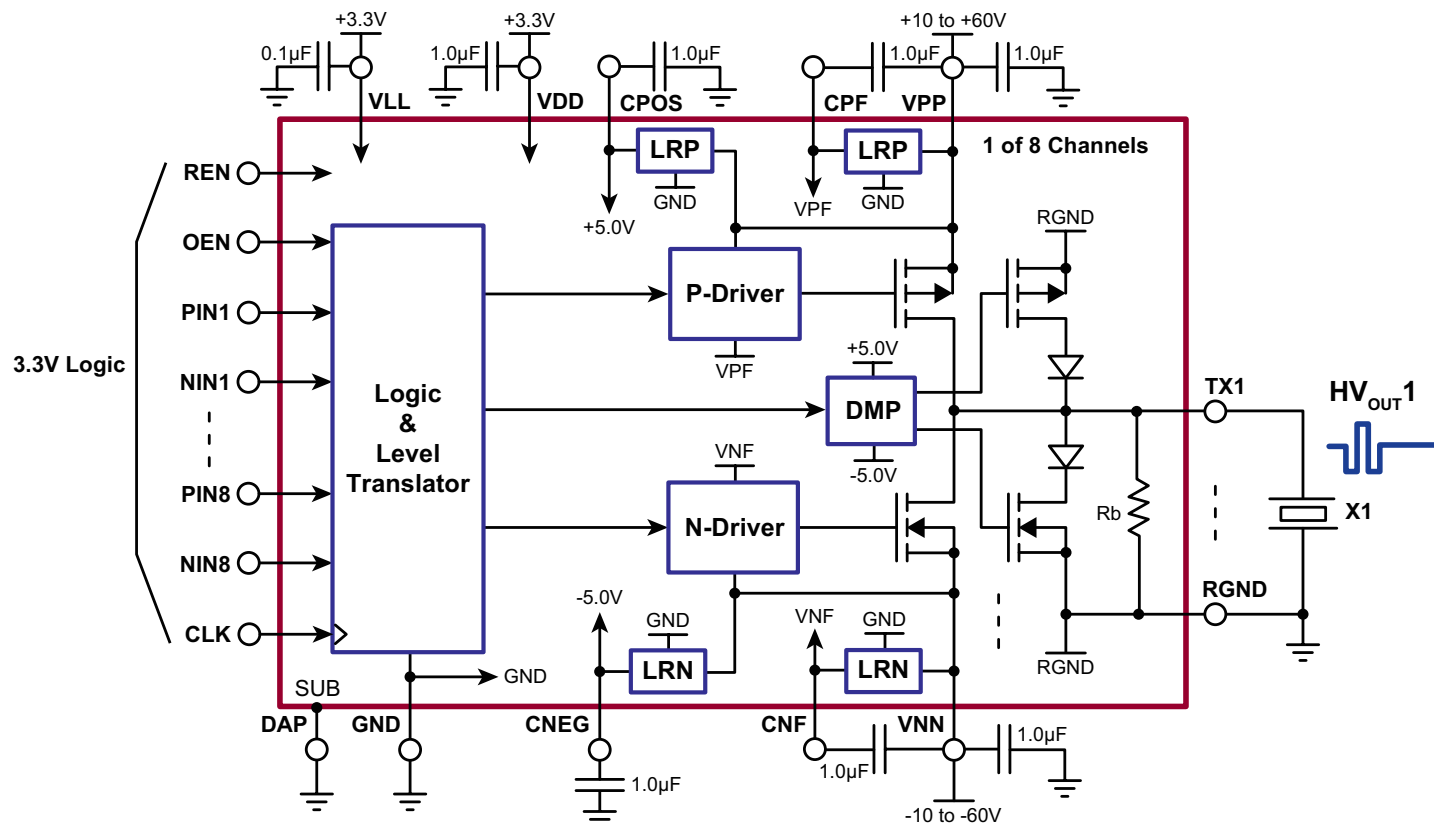
The Supertex HV7350 is an eight channel monolithic high voltage high-speed pulse generator with built-in fast return to zero damping FETs. This high voltage and high-speed integrated circuit is designed for portable medical ultrasound image devices.

HV7350 consists of a controller logic interface circuit, level translators, MOSFET gate drives, and high current power P-channel and N-channel MOSFETs as the output stage for each channel.

The output peak currents of each channel are guaranteed to be over $\pm 1.0A$ with up to $\pm 60V$ pulse swings as well as return-to-zero (RTZ) mode. The gate drivers for the output MOSFETs are powered by built-in linear 5.0V regulators referenced to V_{PP} and V_{NN} . This direct coupling topology of the gate drivers not only saves four floating voltage supplies or AC coupling capacitors per channel, but also makes the PCB layout smaller and easier.

An input clock pin is available to realign all the logic input control lines to a master clock. Precise logic timing is always essential in any ultrasound systems.

Typical Application Circuit



Ordering Information

Part Number	Package	Packing
HV7350K6-G	56-Lead (8x8) QFN	250/ Tray
HV7350K6-G M937	56-Lead (8x8) QFN	2000/Reel

-G denotes a lead (Pb)-free / RoHS compliant package



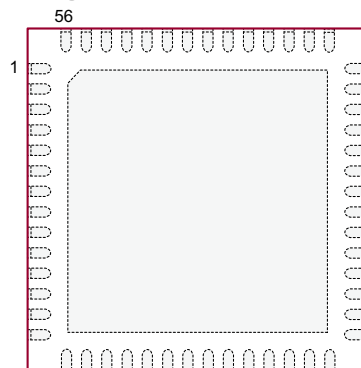
ESD Sensitive Device

Absolute Maximum Ratings

Parameter	Value
V _{SUB} , substrate voltage is GND	0V
V _{LL} , Positive logic supply	-0.5V to +5.5V
V _{DD} , Positive logic and level translator supply	-0.5V to +5.5V
C _{POS} to GND, Positive level translator circuit	-0.5V to +5.5V
C _{NEG} to GND, Negative level translator circuit	+0.5V to -5.5V
(V _{PP} - C _{PF}), Positive gate driver circuit	-0.5V to +5.5V
(C _{NF} - V _{NN}), Negative gate driver circuit	-0.5V to +5.5V
(V _{PP} - V _{NN}) Differential high voltage supply	+130V
V _{PP} , High voltage positive supply	-0.5V to +65V
V _{NN} , High voltage negative supply	+0.5V to -65V
All logic input PIN _x , NIN _x , OEN and REN voltages	-0.5V to +5.5V
Operating temperature	-40°C to 125°C
Storage temperature	-65°C to 150°C

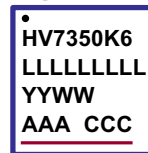
Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Pin Configuration



56-Lead QFN
(top view)

Package Marking



L = Lot Number
 YY = Year Sealed
 WW = Week Sealed
 A = Assembler ID
 C = Country of Origin
 — = "Green" Packaging

Package may or may not include the following marks: Si or

56-Lead QFN

Typical Thermal Resistance

Package	θ_{ja}
56-Lead (8x8) QFN	21°C/W

Output Current & R_{on}

I _{SC}	R _{onP}	R _{onN}	I _{DMP}	R _{onDP}	R _{onDN}
1.5A	13Ω	6.5Ω	1.5A	13Ω	8.0Ω

Notes:

1. V_{PP}/V_{NN} = +/-60V, V_{DD} = +3.3V; REN = 1
2. I_{SC} is current into 1.0Ω to GND;

3. I_{DMP} is current from +/-30V connected to T_x pin.
4. Max pulse width for current measurement on T_x pin is 100ns.

Power-Up Sequence

Step	Description
1	V _{LL} with logic signal low
2	V _{DD}
3	REN = 1 (external supplies on)
4	V _{PP} and V _{NN}
5	Logic control signals active

Note:

Powering up/down in any arbitrary sequence will not cause any damage to the device. The powering up/down sequence is only recommended in order to minimize possible inrush current.

Power-Down Sequence

Step	Description
1	All logic signals go to low
2	V _{PP} and V _{NN}
3	REN = 0 (external supplies off)
4	V _{DD}
5	V _{LL}

Operating Supply Voltages and Current (Eight Active Channels)

(Operating conditions, unless otherwise specified, $V_{LL} = +3.3V$, $V_{DD} = +3.3V$, $V_{PP} = +60V$, $V_{NN} = -60V$, $V_{CLK} = +3.3V$, $T_A = 25^\circ C$)

Sym	Parameter	Min	Typ	Max	Units	Conditions
V_{DD}	V_{DD} voltage supply	2.97	3.30	5.20	V	---
$UVLO_{DD}$	V_{DD} UVLO	2.30	2.60	2.80	V	---
V_{LL}	Logic voltage reference	2.50	3.30	5.00	V	---
$UVLO_{LL}$	V_{LL} UVLO	1.30	1.55	1.70	V	---
V_{PP}	Positive high voltage supply	+10	-	+60	V	---
V_{NN}	Negative high voltage supply	-60	-	-10	V	---
I_{LLQ}	V_{LL} current	-	8.0	-	μA	OEN = REN = 0
I_{DDQ}	V_{DD} current	-	1.0	-		
I_{PPQ}	V_{PP} current	-	5.0	10		
I_{NNQ}	V_{NN} current	-	5.0	10		
I_{LLEN}	V_{LL} current	-	13	20	μA	OEN = REN = 1 5.0ms after f = 0MHz
I_{DDEN}	V_{DD} current	-	480	700		
I_{PPEN}	V_{PP} current	-	220	350		
I_{NNEN}	V_{NN} current	-	300	400		
I_{DDCW}	V_{DD} current	-	2.3	-	mA	f = 5.0MHz, Continuous, no loads, for calculation reference only.
I_{PPCW}	V_{PP} current	-	80	-		
I_{NNCW}	V_{NN} current	-	80	-		
$I_{LL,CLK}$	V_{LL} current	-	33	-	μA	$f_{CLK} = 10MHz$, PIN = NIN = 0

Electrical Characteristics

(Operating conditions, unless otherwise specified, $V_{LL} = +3.3V$, $V_{DD} = +3.3V$, $V_{PP} = +60V$, $V_{NN} = -60V$, $V_{CLK} = +3.3V$, $T_A = 25^\circ C$)

Pulsar P-Channel MOSFET

Sym	Parameter	Min	Typ	Max	Units	Conditions
I_{OUT}	Output saturation current	1.0	1.5	-	A	---
R_{ON}	Channel resistance	-	13.2	-	Ω	$I_{SD} = 100mA$

Pulsar N-Channel MOSFET

Sym	Parameter	Min	Typ	Max	Units	Conditions
I_{OUT}	Output saturation current	1.0	1.5	-	A	---
R_{ON}	Channel resistance	-	8.0	-	Ω	$I_{SD} = 100mA$

Damping P-Channel MOSFET

Sym	Parameter	Min	Typ	Max	Units	Conditions
I_{OUT}	Output saturation current	1.0	1.5	-	A	---
R_{ON}	Channel resistance	-	13	-	Ω	$I_{SD} = 100mA$

Damping N-Channel MOSFET

Sym	Parameter	Min	Typ	Max	Units	Conditions
I_{OUT}	Output saturation current	1.0	1.5	-	A	---
R_{ON}	Channel resistance	-	9.0	-	Ω	$I_{SD} = 100mA$

Logic Inputs

Sym	Parameter	Min	Typ	Max	Units	Conditions
V_{IH}	Input logic high voltage	$0.7 \cdot V_{LL}$	-	V_{LL}	V	$V_{LL} = 2.5$ to $3.3V$
V_{IL}	Input logic low voltage	0	-	$0.3 \cdot V_{LL}$	V	
V_{IH}	Input logic high voltage	$0.8 \cdot V_{LL}$	-	V_{LL}	V	$V_{LL} = 5.0V$
V_{IL}	Input logic low voltage	0	-	$0.2 \cdot V_{LL}$	V	
I_{IH}	Input logic high current	-	-	10	μA	---
I_{IL}	Input logic low current	-10	-	-	μA	---
C_{IN}	Input logic capacitance	-	-	5.0	pF	---

MOSFET Drain Bleed Resistor

Sym	Parameter	Min	Typ	Max	Units	Conditions
R_{B1-8}	Output Bleed Resistance	12	17	25	k Ω	---
P_{RB1-8}	Bleed Resistors Power Limit	-	-	50	mW	---

AC Electrical Characteristics

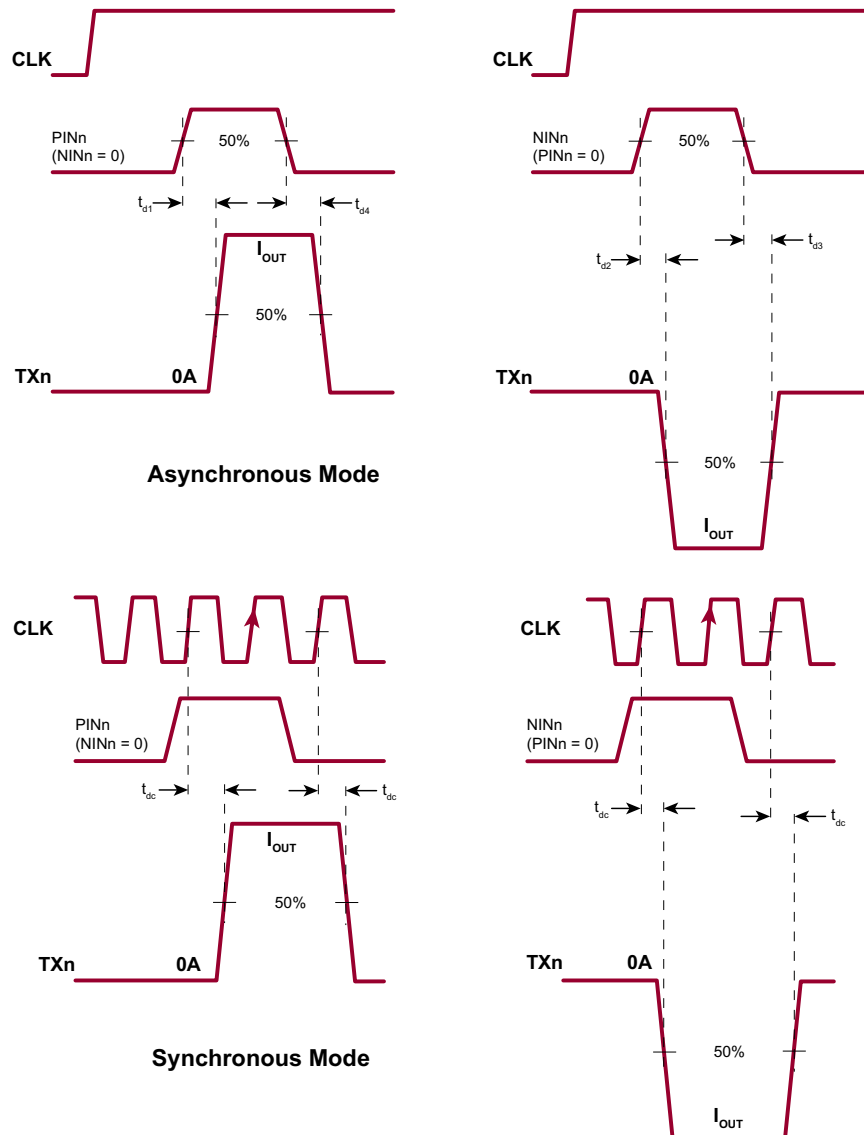
(Operating conditions, unless otherwise specified, $V_{LL} = +3.3V$, $V_{DD} = +3.3V$, $V_{PP} = +60V$, $V_{NN} = -60V$, $V_{CLK} = +3.3V$, $T_A = 25^\circ C$)

Sym	Parameter	Min	Typ	Max	Units	Conditions
t_r	Output rise time	-	30	-	ns	330pF//2.5k Ω load 10 - 90%
t_f	Output fall time	-	30	-	ns	
t_{EN}	Enable time	-	300	500	μs	Cap value see page 1 diagram. OEN = REN
t_{DIS}	Disable time	-	2.8	10	μs	
t_{d1}	Delay time on PIN _x rise	-	12	-	ns	1.0 Ω resistor load, D%<1% (See timing diagram) 50% inputs to 50% T _x current
t_{d2}	Delay time on NIN _x rise	-	12	-		
t_{d3}	Delay time on damping rise	-	12	-		
t_{d4}	Delay time on damping fall	-	12	-		
t_{dc}	Delay time on CLK rise	-	9.0	-		
Δt_{DELAY}	Delay time matching	-	± 3.0	-	ns	P to N, channel to channel
t_j	Delay jitter on rise or fall	-	TBD	-	ps	$V_{PP}/V_{NN} = +/-25V$, input tr 50% to HV _{OUT} t_r or t_f 50%, with 330pF//2.5k Ω load
t_{rr}	RTZ FETs drain diode t_{rr}	-	25	-	ns	$I_F = 1.0A$, $I_R = 1.0A$, $R_L = 10\Omega$
f_{CLK}	Re-timing clock frequency	10	220	-	MHz	---
t_{RC} , t_{FC}	Re-timing clock rise & fall times	-	0.5	5.0	ns	---
t_{su}	Set-up time, PIN/NIN to CLK	2.0	-	-	ns	---
t_H	Hold time, CLK to PIN/NIN	1.0	-	-	ns	---
t_{CLK_LO}	Clock time low	2.0	-	100	ns	CLK input must have at least one pulse before PIN and NIN inputs are not zero. Be sure to return inputs to zero before stopping clock.
t_{CLK_HI}	Clock time high	2.0	-	100	ns	
t_{CLK_REC}	Clock recognition time	-	2.0	-	ns	
t_{CLK_RLS}	Clock release time	150	300	800	ns	
f_{OUT}	Output frequency range	-	-	20	MHz	100 Ω resistor load
HD2	Second harmonic distortion	-	-40	-	dB	
C_{OSS}	Output capacitance	-	50	-	pF	$V_{DS} = 25V$, $f = 1.0MHz$, of T _x pin total

Truth Table

Logic Inputs				TX _n Output			Note
OEN	CLK	PIN _x	NIN _x	VPP	VNN	RGND	
1	VLL	0	0	OFF	OFF	ON	Asynchronous Mode Output change on PIN/NIN
1	VLL	1	0	ON	OFF	OFF	
1	VLL	0	1	OFF	ON	OFF	
1	VLL	1	1	OFF	OFF	OFF	
1	⌋	0	0	OFF	OFF	ON	Synchronous Mode Output change at retiming clock(CLK) rising edge, registered by PIN/NIN
1	⌋	1	0	ON	OFF	OFF	
1	⌋	0	1	OFF	ON	OFF	
1	⌋	1	1	OFF	OFF	OFF	
0	X	X	X	OFF	OFF	OFF	Disabled

Switching Time Diagram



Pin Description

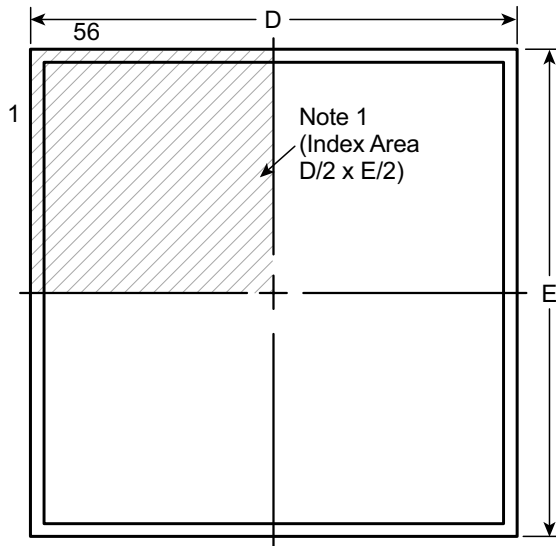
Pin	Name	Description
1	PIN2	Input logic control of high voltage output P-FET for channel 2, Hi = on, Low = off. (see logic table)
2	NIN2	Input logic control of high voltage output N-FET for channel 2, Hi = on, Low = off. (see logic table)
3	PIN3	Input logic control of high voltage output P-FET for channel 3, Hi = on, Low = off. (see logic table)
4	NIN3	Input logic control of high voltage output N-FET for channel 3, Hi = on, Low = off. (see logic table)
5	PIN4	Input logic control of high voltage output P-FET for channel 4, Hi = on, Low = off. (see logic table)
6	NIN4	Input logic control of high voltage output N-FET for channel 4, Hi = on, Low = off. (see logic table)
7	OEN	Output enable Hi = on, Low = off. See logic truth table
8	REN	Built-in positive and negative 5V voltage regulators enable. Hi = on, Low = off. If REN = 0, external floating 5V power supplies may be supplied across CPF, CNF CPOS and CNEG capacitors
9	PIN5	Input logic control of high voltage output P-FET for channel 5, Hi = on, Low = off. (see logic table)
10	NIN5	Input logic control of high voltage output N-FET for channel 5, Hi = on, Low = off. (see logic table)
11	PIN6	Input logic control of high voltage output P-FET for channel 6, Hi = on, Low = off. (see logic table)
12	NIN6	Input logic control of high voltage output N-FET for channel 6, Hi = on, Low = off. (see logic table)
13	PIN7	Input logic control of high voltage output P-FET for channel 7, Hi = on, Low = off. (see logic table)
14	NIN7	Input logic control of high voltage output N-FET for channel 7, Hi = on, Low = off. (see logic table)
15	PIN8	Input logic control of high voltage output P-FET for channel 8, Hi = on, Low = off. (see logic table)
16	NIN8	Input logic control of high voltage output N-FET for channel 8, Hi = on, Low = off. (see logic table)
17	VLL	Logic supply voltage and reference input (+3.3V)
18	GND	Logic and circuit return ground (0V)
19	VDD	Positive voltage power supply (+3.3V)
20	VPP	Positive high voltage power supply (+10 to +60V)
21	VPP	
22	VPP	
23	CPF	Built-in linear voltage VPF regulator output decoupling capacitor pin, 1uF from VPP to CPF per each
24	CNF	Built-in linear voltage VNF regulator output decoupling capacitor pin, 1uF from CNF to VNN per each
25	VNN	Negative high voltage power supply (-10 to -60V)
26	VNN	
27	VNN	
28	TX8	T _x pulser channel 8 output
29	RGND	Damping ground and bleed resistors common return ground
30	TX7	T _x pulser channel 7 output
31	RGND	Damping ground and bleed resistors common return ground
32	TX6	T _x pulser channel 6 output

Pin Description (cont.)

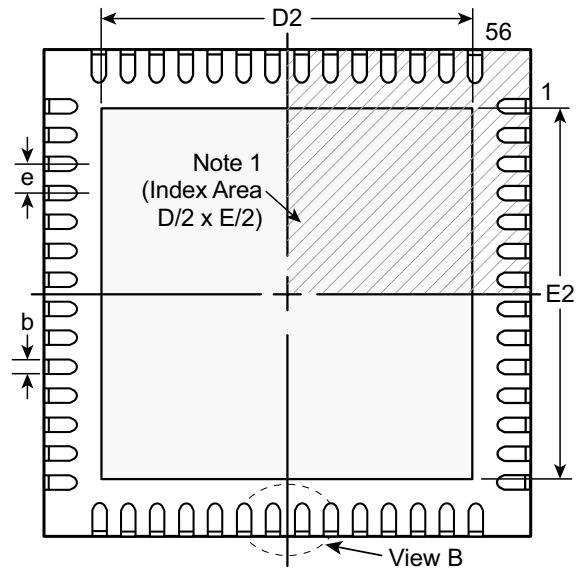
Pin	Name	Description
33	RGND	Damping ground and bleed resistors common return ground
34	TX5	T _x pulser channel 5 output
35	CNEG	Built-in linear voltage -5V regulator output decoupling capacitor pin, 1.0uF from CNEG to GND
36	CPOS	Built-in linear voltage +5V regulator output decoupling capacitor pin, 1.0uF from CPOS to GND
37	TX4	T _x pulser channel 4 output
38	RGND	Damping ground and bleed resistors common return ground
39	TX3	T _x pulser channel 3 output
40	RGND	Damping ground and bleed resistors common return ground
41	TX2	T _x pulser channel 2 output
42	RGND	Damping ground and bleed resistors common return ground
43	TX1	T _x pulser channel 1 output
44	VNN	Negative high voltage power supply (-10 to -60V)
45	VNN	
46	VNN	
47	CNF	Built-in linear voltage VNF regulator output decoupling capacitor pin, 1uF from CNF to VNN per each
48	CPF	Built-in linear voltage VPF regulator output decoupling capacitor pin, 1uF from VPP to CPF per each
49	VPP	Positive high voltage power supply (+10 to +60V)
50	VPP	
51	VPP	
52	VDD	Positive voltage power supply (+3.3V)
53	GND	Logic and circuit return ground (0V)
54	CLK	Re-timing register clock input. Connect to V _{LL} to disable the re-timing function
55	PIN1	Input logic control of high voltage output P-FET for channel 1, Hi = on, Low = off. (see logic table)
56	NIN1	Input logic control of high voltage output N-FET for channel 1, Hi = on, Low = off. (see logic table)
VSUB (Thermal Pad)		Substrate bottom is internally connected to the central thermal pad on the bottom of package. It must be connected to GND (0V) externally

56-Lead QFN Package Outline (K6)

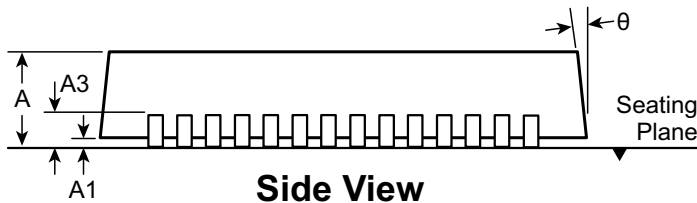
8.00x8.00mm body, 1.00mm height (max), 0.50mm pitch



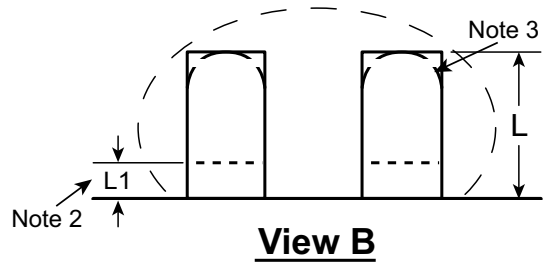
Top View



Bottom View



Side View



View B

Notes:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.
2. Depending on the method of manufacturing, a maximum of 0.15mm pullback (L1) may be present.
3. The inner tip of the lead may be either rounded or square.

Symbol	A	A1	A3	b	D	D2	E	E2	e	L	L1	θ	
Dimension (mm)	MIN	0.80	0.00	0.20 REF	0.18	7.85*	2.75	7.85*	2.75	0.50 BSC	0.30	0°	
	NOM	0.90	0.02		0.25	8.00	5.70	8.00	5.70		0.40	-	-
	MAX	1.00	0.05		0.30	8.15*	6.70†	8.15*	6.70†		0.50	0.15	14°

JEDEC Registration MO-220, Variation VLLD-2, Issue K, June 2006.

* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

Drawings are not to scale.

Supertex Doc.#: DSPD-56QFNK68X8P050, Version A031010.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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